

Restriction of Hazardous Substance (RoHS) Certificate of Compliance

For more information, see

http://www.lsi.com/ehs

RoHS Certificate of Compliance Provided By:

Supplier Name: LSI Corporation

Supplier Address: 1320 Ridder Park Drive, San Jose, CA 95131 USA

LSI Part Number: Marketing Model Name / Product Description: 05-25528-02 LSI00438 MR SAS 9380-8e, SINGLE KIT

Hazardous Substance Statement(s): RoHS Definition: Quantity limit of 0.1 % by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr-6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01 % by mass (100 PPM) of homogeneous material for Cadmium RoHS Declaration: Product(s) does not contain RoHS restricted substances per the definition above. Product does contain RoHS restricted substances above the limits per the definition above and is not under an EU RoHS Exemption. Product or product component(s) does not contain RoHS restricted substances per the definition above except for specific EU RoHS Exemptions listed to the right. Product is obsolete or unknown, no information is available. Antimony-Free and Halogen-Free Declarations: Product does not contain above 0.09 % by mass (900 PPM) in homogeneous material for Antimony (Sb). Product does not contain above 0.09 % by mass (900 PPM) in homogeneous material for Bromine (Br) and Chlorine (Cl) and less than 0.15% (1,500 PPM) Br and Cl.	Product or product component(s) meet the following EU RoHS Directive 2011/65/EU Annex III specific exemption(s): 5(a) Lead in glass of cathode ray tubes. 5(b) Lead in glass of gluorescent tubes not exceeding 0.2% by weight. 6(a) Lead as an alloying element in steel for machining purposed and in galvanised steel containing up to 0.35% lead by weight. 6(b) Lead as an alloying element in aluminium containing up to 0.4% lead by weight. 6(c) Copper alloy containing up to 4% lead by weight. 7(a) Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead). 7(b) Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission, and network management for tele-communications. 7(c)-1 Electrical and electronic compounents containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound. 7(c)-1I Lead in dielectric ceramic in capacitors for a rated voltage of 125V AC or 250V DC or higher. 7(c)-1V Lead in Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors. 13(a) Lead in white glasses used for optical application. 15 Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages.
knowledge and belief, as of the date that LSI completes this form. LSI acknowledges that Con implement the RoHS Directive 2011/65/EU. Company acknowledges that LSI may have relied However, in situations where LSI has not independently verified information provided by others, the certification in this paragraph. If the Company and the LSI enter into a written agreement	tive substances using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its inpany will rely on this certification in determining the compliance of its products with European Union member state laws that on information provided by others in completing this form, and that LSI may not have independently verified such information. LSI agrees that, at a minimum, it has a program in place to ensure that its suppliers' certifications are at least as comprehensive as with respect to the identified product, the terms and conditions of that agreement, including any warranty rights and/or remedies the Company's remedies for issues that arise regarding information that LSI provides in this form. Date: 3/7/2014 Title: Environmental Compliance Engineer

Form: EUROHSCOC-E Issue #8, dated 03 May 2013